DOCUMENT CHANGE REQUEST

DCR number 1566	Changes required for: General	Originator: Steve Thacker	
Date: 2024/02/12	Date sent: 2023/04/04	Organisation: ESCC Executive Secretariat	
Status: IMPLEMENTED			

Title:	Evaluation Test Programme for Integrated Circuits: Monolithic Microcircuits, Wire-bonded, Plastic		
Number:	2269030	Issue:	1

Other documents affected:

25200-4, 9030-2

Page:

As per current spec issue above; see also below & attached

Paragraph:

See Below

Original wording:

As per current spec issue above

Proposed wording:

In ESCC 25200:
Changes to implement SAM reject criteria per current ESCC9030 Para. 8.6 (& ESCC226903 Para 6.6) in new Para. 7.7: see attached for details (with changes highlighted yellow):
i.e. Para. 1.2, 2.1, new Para. 7.7

Additional:
ESCC9030 Para. 8.6 & ESCC2269030 Para. 6.6 are amended to remove these same additional reject criteria.
see attached for details (with changes highlighted yellow)

Justification:

to move the additional reject criteria for plastic encapsulated ICs from ESCC 9030 & 2269030 to 25200 as required by the 9000P Working Group.

Attachments:
escc9030iss_draft_2a_in_review.docx, escc25200iss_draft_4a_in_review.docx, escc2269030iss_draft_2a_in_review.docx
Modifications:
§7.1 has a typo. It writes “relative chances of the delamination area of more than 10%...” but it actually means “relative changes”.
Approval signature:
Date signed:
2024-02-12